SDFS095B - NOVEMBER 1993 - REVISED JANUARY 1996

- 3-State Outputs Drive Bus Lines or Buffer-Memory Address Registers
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs

description

This octal buffer and line driver is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The 25- Ω resistors in the lower output circuit reduce ringing and eliminate the need for external resistors.

The SN74F2244 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each buffer)

INP	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z

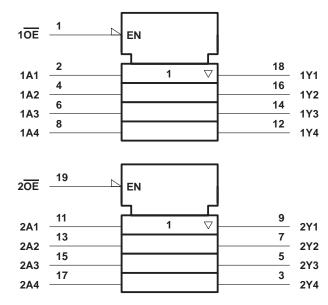
DW OR N PACKAGE (TOP VIEW)

1 <u>OE</u> [1	U	20	vcc
1A1 [2		19	V _{CC} 20E
2Y4 [3		18] 1Y1
1A2 [4		17	2A4
2Y3 [5		16	1Y2
1A3 [6		15	2A3
2Y2 [7		14	1Y3
1A4 [8		13	2A2
2Y1 [9		12	1Y4
GND [10		11	2A1



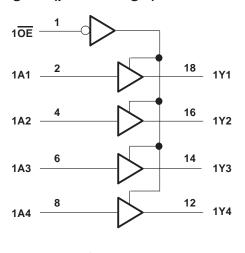
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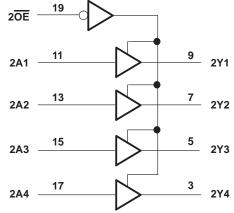
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input voltage range, V _I (see Note 1)	\dots $$ –1.2 V to 7 V
Input current range, I ₁	-30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state, VO	. $$ –0.5 V to 5.5 V
Voltage range applied to any output in the high state, V _O	-0.5 V to V_{CC}
Current into any output in the low state, I _O	30 mA
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stg}	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded if the input current ratings are observed.



recommended operating conditions

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
lıK	Input clamp current			-18	mA
ЮН	High-level output current			– 15	mA
lOL	Low-level output current			12	mA
TA	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER VIK		PARAMETER TEST CONDITIONS [†]			TYP [†]	MAX	UNIT
		V _{CC} = 4.5 V,	I _I = –18 mA			-1.2	V
		V _{CC} = 4.5 V,	I _{OH} = – 3 mA	2.4	2.8		
Vон		V _{CC} = 4.5 V	I _{OH} = – 15 mA	2	2.3		V
J		V _{CC} = 4.75 V,	I _{OH} = – 3 mA	2.7			
.,		V _{CC} = 4.5 V,	I _{OL} = 1 mA		0.2	0.5	
VOL		V _{CC} = 4.5 V,	I _{OL} = 12 mA		0.5	0.75	V
Ц		V _{CC} = 5.5 V,	V _I = 0.5 V			0.1	mA
lozh		V _{CC} = 5.5 V,	V _O = 7 V			50	μΑ
lozL		V _{CC} = 5.5 V,	V _O = 2.7 V			-50	μΑ
lіН		V _{CC} = 5.5 V,	V _I = 2.7 V			20	μΑ
	Any OE input	V 55V				- 1	
IIL	Any A input	V _{CC} = 5.5 V,	$V_{ } = 0.5 V$			- 1.6	mA
los‡		V _{CC} = 5.5 V,	V _O = 0	-100		-225	mA
		.,,	Outputs high		40	60	
ICC	V _{CC} = 5.5 V, Outputs open	Outputs low		60	90	mA	
		Calpais open	Outputs disabled		60	90	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

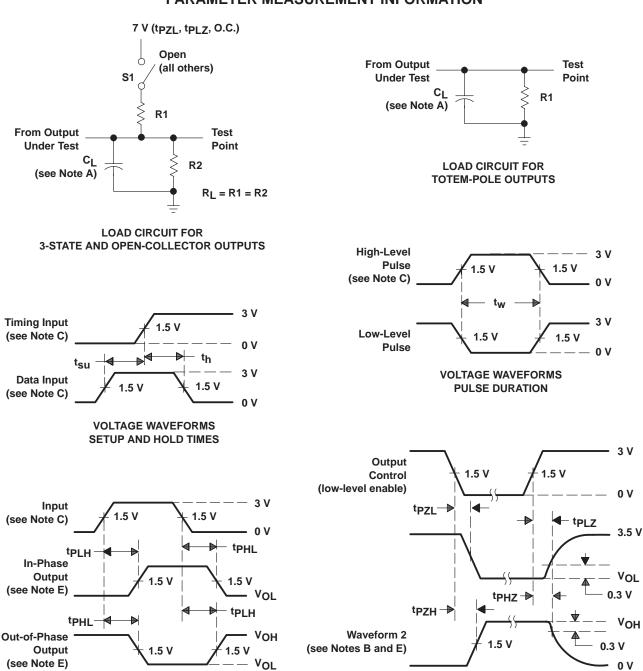
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = C _L = 50 R ₁ = 50 T _A = 25	0 PF, 00 Ω, 00 Ω,	V _{CC} = 4.5 C _L = 50 Pl R ₁ = 500 Ω R ₂ = 500 Ω T _A = MIN	<u>),</u> <u>)</u> ,	UNIT
			MIN	MAX	MIN	MAX	
^t PLH		A Y	1.5	7	1.5	7	
^t PHL	А		2.5	8	2	8	ns
^t PZH	ŌĒ	V	1.5	9	1	9.5	
t _{PZL}	OE	Y	2.5	11.5	2.5	12	ns
^t PHZ	ŌĒ	V	1.5	9	1	9.5	ns
^t PLZ	OE	ſ	1.5	8.5	1.5	9.5	115

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

VOLTAGE WAVEFORMS

PROPAGATION DELAY TIMES (see Note D)

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $t_f = t_f \leq$ 2.5 ns, duty cycle = 50%.

VOLTAGE WAVEFORMS

ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- D. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74F2244DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	Samples Not Available
SN74F2244DBR	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	Samples Not Available
SN74F2244DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	Samples Not Available
SN74F2244DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	Samples Not Available
SN74F2244N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	Samples Not Available

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



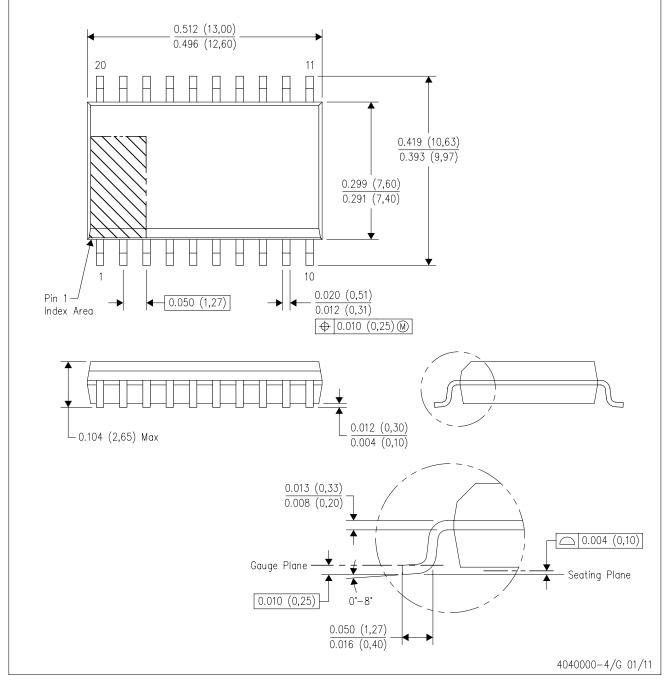
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

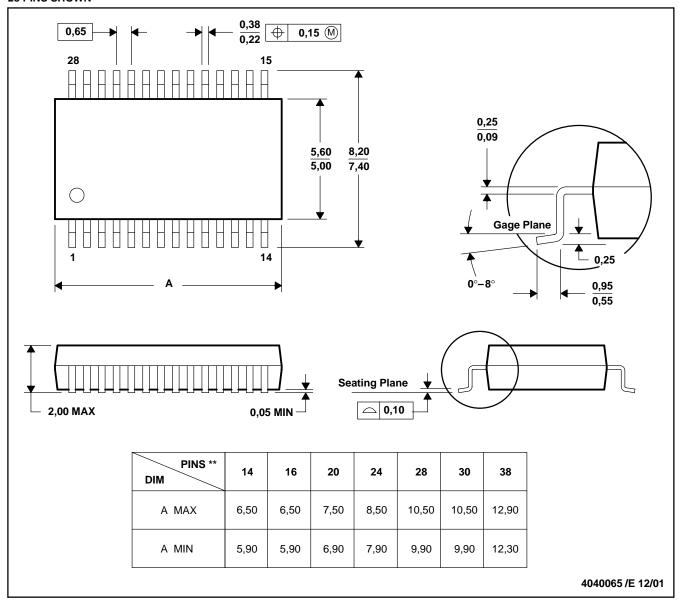
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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